

FEATURES

- **Tiny: 4 DACs in the Board Space of an S0-8**
- **Micropower: 59µA per DAC Plus 1µA Sleep Mode for Extended Battery Life**
- **Wide 2.7V to 5.5V Supply Range**
- **Rail-to-Rail Voltage Outputs Drive 1000pF**
- Reference Range Includes Supply for Ratiometric 0V to V_{CC} Output
- **Reference Input Impedance is Code-Independent —Eliminates External Reference Buffer**
- Individually Addressable DACs
- Differential Nonlinearity: $\leq \pm 0.75\text{LSB}$ Max
- Pin-Compatible Octal Version Available (LTC1660)

APPLICATIONS

- Mobile Communications
- Remote Industrial Devices
- Automatic Calibration for Manufacturing
- Portable Battery-Powered Instruments
- Trim/Adjust Applications

DESCRIPTION

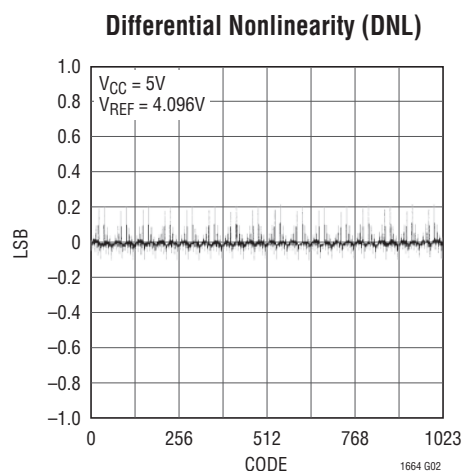
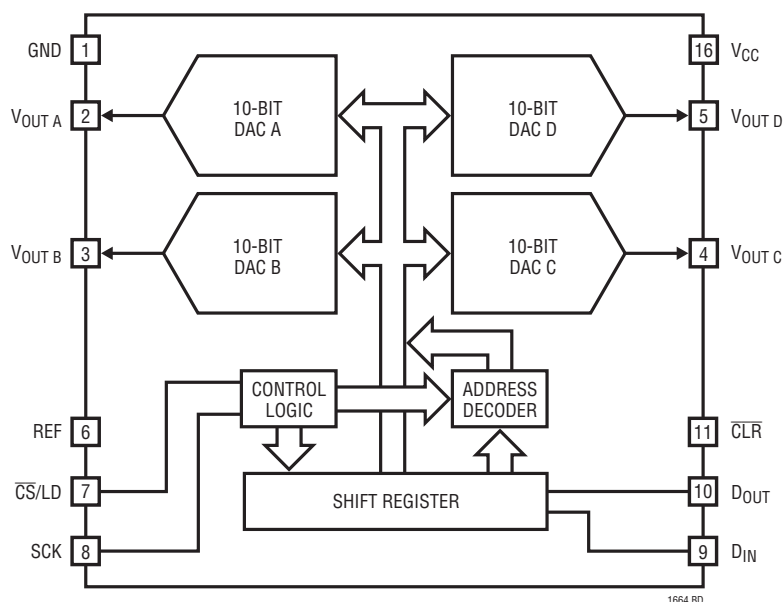
The LTC[®]1664 integrates four accurate, serially addressable 10-bit digital-to-analog converters (DACs) in a tiny 16-pin narrow SSOP package. Each buffered DAC draws just 59µA total supply current, yet is capable of supplying DC output currents in excess of 5mA and reliably driving capacitive loads of up to 1000pF. Sleep mode further reduces total supply current to 1µA.

Linear Technology's proprietary, inherently monotonic voltage interpolation architecture provides excellent linearity while allowing for an exceptionally small external form factor.

Ultralow supply current, power-saving sleep mode and extremely compact size make the LTC1664 ideal for battery-powered applications, while its ease of use, high performance and wide supply range make it an excellent choice as a general-purpose converter.

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BLOCK DIAGRAM



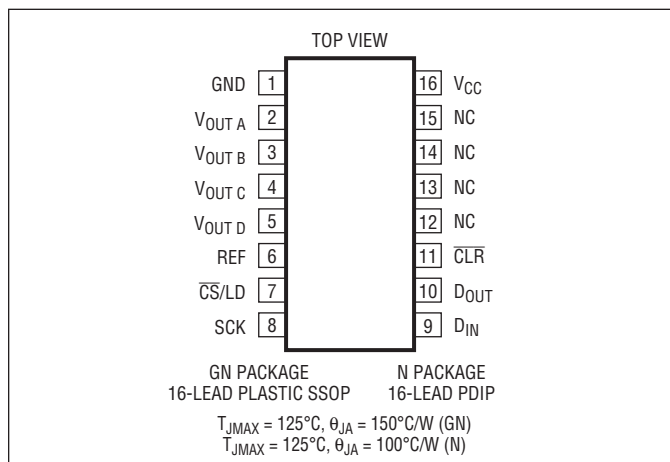
LTC1664

ABSOLUTE MAXIMUM RATINGS

(Note 1)

V_{CC} to GND	–0.3V to 7.5V
Logic Inputs to GND	–0.3V to 7.5V
$V_{OUT A}$, $V_{OUT B}$... $V_{OUT D}$, REF to GND	–0.3V to ($V_{CC} + 0.3V$)
Maximum Junction Temperature	125°C
Operating Temperature Range	
LTC1664C	0°C to 70°C
LTC1664I	–40°C to 85°C
Storage Temperature Range	–65°C to 150°C
Lead Temperature (Soldering, 10 sec)	300°C

PIN CONFIGURATION



ORDER INFORMATION

LEAD FREE FINISH	TAPE AND REEL	PART MARKING	PACKAGE DESCRIPTION	TEMPERATURE RANGE
LTC1664CGN#PBF	LTC1664CGN#TRPBF	1664	16-Lead Plastic SSOP	0°C to 70°C
LTC1664CN#PBF	LTC1664CN#TRPBF	LTC1664CN	16-Lead PDIP	0°C to 70°C
LTC1664IGN#PBF	LTC1664IGN#TRPBF	1664I	16-Lead Plastic SSOP	–40°C to 85°C
LTC1664IN#PBF	LTC1664IN#TRPBF	LTC1664IN	16-Lead PDIP	–40°C to 85°C
LEAD BASED FINISH	TAPE AND REEL	PART MARKING	PACKAGE DESCRIPTION	TEMPERATURE RANGE
LTC1664CGN	LTC1664CGN#TR	1664	16-Lead Plastic SSOP	0°C to 70°C
LTC1664CN	LTC1664CN#TR	LTC1664CN	16-Lead PDIP	0°C to 70°C
LTC1664IGN	LTC1664IGN#TR	1664I	16-Lead Plastic SSOP	–40°C to 85°C
LTC1664IN	LTC1664IN#TR	LTC1664IN	16-Lead PDIP	–40°C to 85°C

Consult LTC Marketing for parts specified with wider operating temperature ranges.

For more information on lead free part marking, go to: <http://www.linear.com/leadfree/>

For more information on tape and reel specifications, go to: <http://www.linear.com/tapeandreel/>

ELECTRICAL CHARACTERISTICS The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{CC} = 2.7\text{V}$ to 5.5V , $V_{REF} \leq V_{CC}$, V_{OUT} unloaded, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Accuracy							
	Resolution		●	10			Bits
	Monotonicity	(Notes 2, 4)	●	10			Bits
DNL	Differential Nonlinearity	(Notes 2, 4)	●		± 0.2	± 0.75	LSB
INL	Integral Nonlinearity	(Notes 2, 4)	●		± 0.6	± 2.5	LSB
V_{OS}	Offset Error	(Note 7)	●		± 10	± 30	mV
	V_{OS} Temperature Coefficient		●		± 15		$\mu\text{V}/^\circ\text{C}$
FSE	Full-Scale Error	$V_{CC} = 5\text{V}$, $V_{REF} = 4.096\text{V}$ (Note 4)	●		± 3	± 15	LSB
	Full-Scale Error Temperature Coefficient		●		± 30		$\mu\text{V}/^\circ\text{C}$
PSR	Power Supply Rejection	$V_{REF} = 2.5\text{V}$			0.18		LSB/V
Reference Input							
	Input Voltage Range		●	0		V_{CC}	V
	Resistance	Not in Sleep Mode	●	70	130		$\text{k}\Omega$
	Capacitance				12		pF
I_{REF}	Reference Current	Sleep Mode	●		0.001	1	μA
Power Supply							
V_{CC}	Positive Supply Voltage		●	2.7		5.5	V
I_{CC}	Supply Current	$V_{CC} = 5\text{V}$ (Note 3)	●		236	380	μA
		$V_{CC} = 3\text{V}$ (Note 3)	●		186	290	μA
		Sleep Mode (Note 3)	●		1	3	μA
DC Performance							
	Short-Circuit Current Low	$V_{OUT} = 0\text{V}$, $V_{CC} = 5.5\text{V}$, $V_{REF} = 5.1\text{V}$, Code = 1023 (Note 9)	●	10	30	100	mA
	Short-Circuit Current High	$V_{OUT} = V_{CC} = 5.5\text{V}$, $V_{REF} = 5.1\text{V}$, Code = 0 (Note 9)	●	10	27	120	mA
AC Performance							
	Voltage Output Slew Rate	Rising (Notes 4, 5) Falling (Notes 4, 5)			0.60 0.25		$\text{V}/\mu\text{s}$ $\text{V}/\mu\text{s}$
	Voltage Output Settling Time	Rising $0.1V_{FS}$ to $0.9V_{FS} \pm 0.5\text{LSB}$ (Notes 4, 5) Falling $0.9V_{FS}$ to $0.1V_{FS} \pm 0.5\text{LSB}$ (Notes 4, 5)			6 19		μs μs
	Capacitive Load Driving				1000		pF
Digital I/O							
V_{IH}	Digital Input High Voltage	$V_{CC} = 2.7\text{V}$ to 5.5V $V_{CC} = 2.7\text{V}$ to 3.6V	● ●	2.4 2.0			V V
V_{IL}	Digital Input Low Voltage	$V_{CC} = 4.5\text{V}$ to 5.5V $V_{CC} = 2.7\text{V}$ to 5.5V	● ●			0.8 0.6	V V
V_{OH}	Digital Output High Voltage	$I_{OUT} = -1\text{mA}$, D_{OUT} Only	●	$V_{CC} - 1$			V
V_{OL}	Digital Output Low Voltage	$I_{OUT} = 1\text{mA}$, D_{OUT} Only	●			0.4	V
I_{LK}	Digital Input Leakage	$V_{IN} = \text{GND}$ to V_{CC}	●		0.05	± 10	μA
C_{IN}	Digital Input Capacitance				2		pF

TIMING CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. (Figure 1)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
$V_{CC} = 4.5\text{V to } 5.5\text{V}$							
t_1	D_{IN} Valid to SCK Setup		●	40			ns
t_2	D_{IN} Valid to SCK Hold		●	0			ns
t_3	SCK High Time	(Note 6)	●	30			ns
t_4	SCK Low Time	(Note 6)	●	30			ns
t_5	$\overline{CS}/LD$ Pulse Width	(Note 6)	●	80			ns
t_6	LSB SCK High to $\overline{CS}/LD$ High	(Note 6)	●	30			ns
t_7	$\overline{CS}/LD$ Low to SCK High	(Note 6)	●	80			ns
t_8	D_{OUT} Propagation Delay	$C_{LOAD} = 15\text{pF}$ (Note 6)	●	5		80	ns
t_9	SCK Low to $\overline{CS}/LD$ Low	(Note 6)	●	20			ns
t_{10}	CLR Pulse Width	(Note 6)	●	100			ns
t_{11}	$\overline{CS}/LD$ High to SCK Positive Edge	(Note 6)	●	30			ns
	SCK Frequency	(Notes 6 and 8)	●			16.7	MHz
$V_{CC} = 2.7\text{V to } 5.5\text{V}$							
t_1	D_{IN} Valid to SCK Setup	(Note 6)	●	60			ns
t_2	D_{IN} Valid to SCK Hold	(Note 6)	●	0			ns
t_3	SCK High Time	(Note 6)	●	50			ns
t_4	SCK Low Time	(Note 6)	●	50			ns
t_5	$\overline{CS}/LD$ Pulse Width	(Note 6)	●	100			ns
t_6	LSB SCK High to $\overline{CS}/LD$ High	(Note 6)	●	50			ns
t_7	$\overline{CS}/LD$ Low to SCK High	(Note 6)	●	100			ns
t_8	D_{OUT} Propagation Delay	$C_{LOAD} = 15\text{pF}$ (Note 6)	●	5		150	ns
t_9	SCK Low to $\overline{CS}/LD$ Low	(Note 6)	●	30			ns
t_{10}	CLR Pulse Width	(Note 6)	●	120			ns
t_{11}	$\overline{CS}/LD$ High to SCK Positive Edge	(Note 6)	●	30			ns
	SCK Frequency	(Notes 6 and 8)	●			10	MHz

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Note 2: Nonlinearity and monotonicity are defined and tested at $V_{CC} = 5\text{V}$, $V_{REF} = 4.096\text{V}$, from code 20 to code 1023. See the Rail-to-Rail Output Considerations section.

Note 3: Digital inputs at 0V or V_{CC} .

Note 4: Load is $10\text{k}\Omega$ in parallel with 100pF .

Note 5: $V_{CC} = V_{REF} = 5\text{V}$.

Note 6: Guaranteed by design and not subject to test.

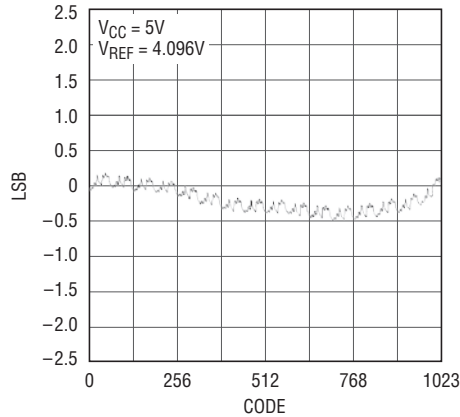
Note 7: Measured at code 20.

Note 8: If a continuous clock is used, $\overline{CS}/LD$ timing (t_7 and t_9) will limit the maximum clock frequency to 5MHz at 4.5V to 5.5V (3.85MHz at 2.7V to 5.5V).

Note 9: Any output shorted.

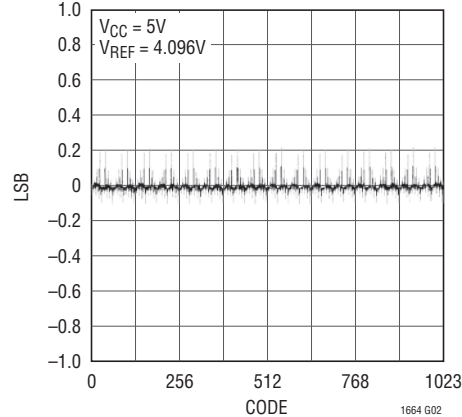
TYPICAL PERFORMANCE CHARACTERISTICS

Integral Nonlinearity (INL)



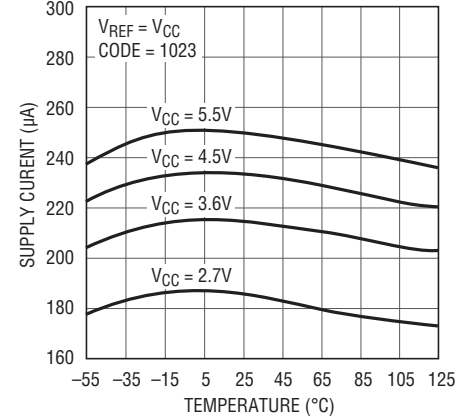
1664 G01

Differential Nonlinearity (DNL)



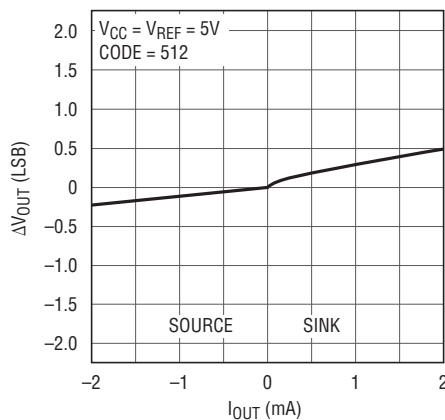
1664 G02

Supply Current vs Temperature



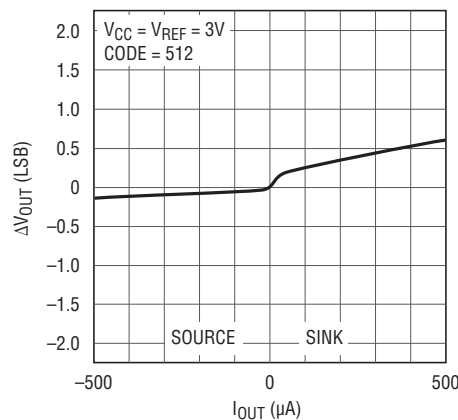
1664 G03

Load Regulation vs Output Current



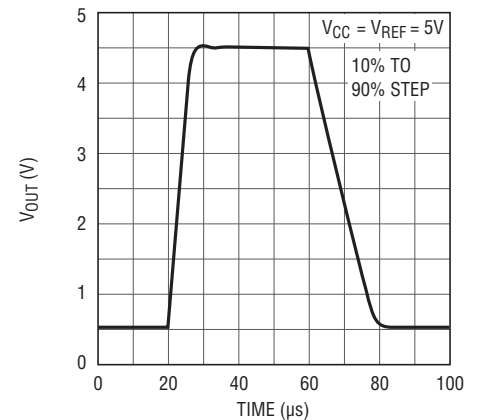
1664 G04

Load Regulation vs Output Current



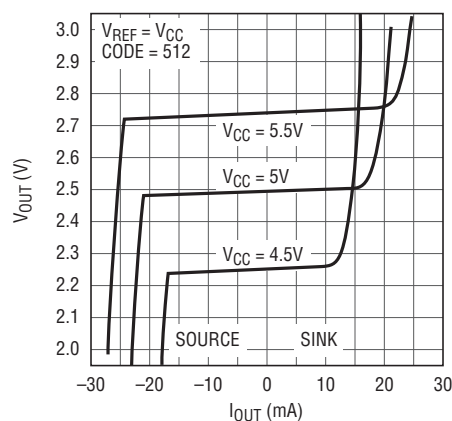
1664 G05

Large-Signal Step Response



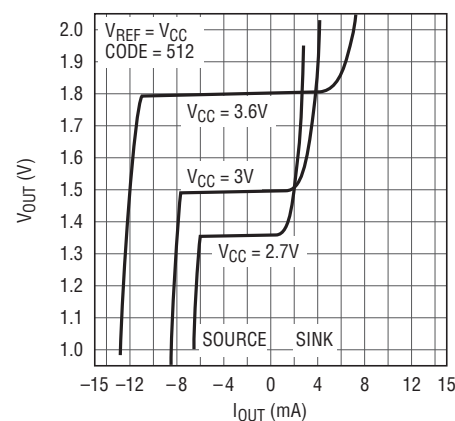
1664 G06

Mid-Scale Output Voltage vs Load Current



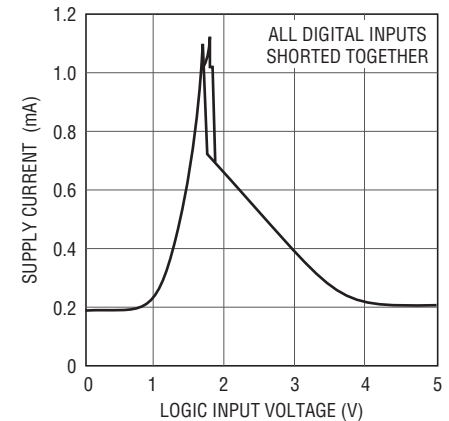
1664 G07

Mid-Scale Output Voltage vs Load Current



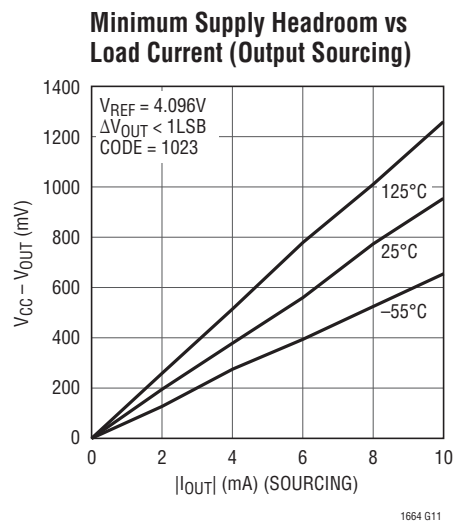
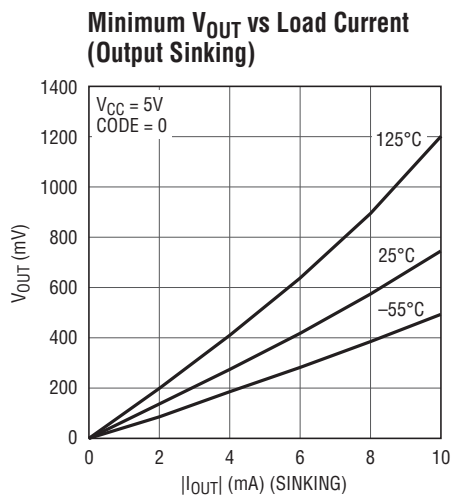
1664 G08

Supply Current vs Logic Input Voltage



1664 G09

TYPICAL PERFORMANCE CHARACTERISTICS



PIN FUNCTIONS

GND (Pin 1): System Ground.

V_{OUTA} to V_{OUTD} (Pins 2–5): DAC Analog Voltage Outputs. The output range is:

$$0 \text{ to } \left(\frac{1023}{1024} \right) V_{REF}$$

REF (Pin 6): Reference Voltage Input. $0V \leq V_{REF} \leq V_{CC}$.

$\overline{CS}/LD$ (Pin 7): Serial Interface Chip Select/Load Input. When $\overline{CS}/LD$ is low, SCK is enabled for shifting data on D_{IN} into the register. When $\overline{CS}/LD$ is pulled high, SCK is disabled and data is loaded from the shift register into the specified DAC register(s), updating the analog output(s). CMOS and TTL compatible.

SCK (Pin 8): Serial Interface Clock Input. CMOS and TTL compatible.

D_{IN} (Pin 9): Serial Interface Data Input. Data on the D_{IN} pin is shifted into the 16-bit register on the rising edge of SCK. CMOS and TTL compatible.

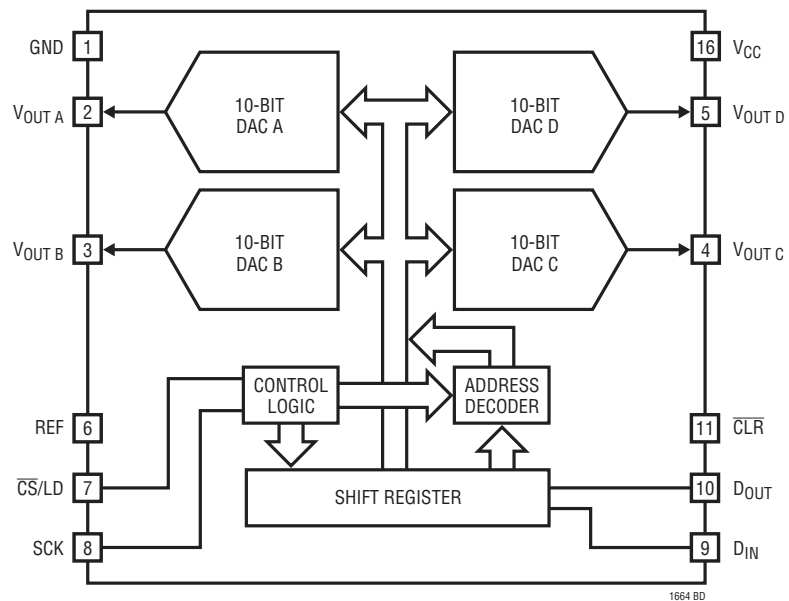
D_{OUT} (Pin 10): Serial Interface Data Output. Data appears on D_{OUT} 16 positive SCK edges after being applied to D_{IN} . May be tied to D_{IN} of another serial device for daisy-chain operation. CMOS and TTL compatible.

$\overline{CLR}$ (Pin 11): Asynchronous Clear Input. All internal shift and DAC registers are cleared to zero at the falling edge of the $\overline{CLR}$ signal, forcing the analog outputs to zero-scale. CMOS and TTL compatible.

NC (Pins 12–15): Make no electrical connection to these pins.

V_{CC} (Pin 16): Supply Voltage Input. $2.7V \leq V_{CC} \leq 5.5V$.

BLOCK DIAGRAM



TIMING DIAGRAM

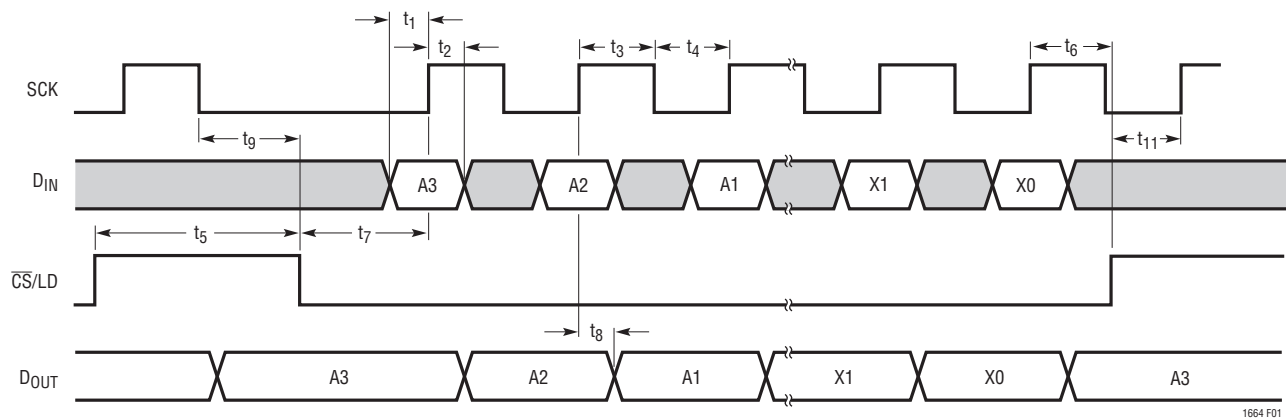


Figure 1

OPERATION

Transfer Function

The transfer function is

$$V_{\text{OUT(IDEAL)}} = \left(\frac{k}{1024} \right) V_{\text{REF}}$$

where k is the decimal equivalent of the binary DAC input code and V_{REF} is the voltage at REF (Pin 6).

Power-On Reset

The LTC1664 clears the outputs to zero-scale when power is first applied, making system initialization consistent and repeatable.

Power Supply Sequencing

The voltage at REF (Pin 6) should be kept within the range $-0.3\text{V} \leq V_{\text{REF}} \leq V_{\text{CC}} + 0.3\text{V}$ (see Absolute Maximum Ratings). Particular care should be taken to observe these limits during power supply turn-on and turn-off sequences, when the voltage at V_{CC} (Pin 16) is in transition. If it is not possible to sequence the supplies, connect a Schottky diode from REF (anode) to V_{CC} (cathode).

Serial Interface

Referring to Figure 2: With $\overline{\text{CS/LD}}$ held low, data on the D_{IN} input is shifted into the 16-bit shift register on the positive edge of SCK. The 4-bit DAC address, A3-A0, is loaded first (see Table 2), then the 10-bit input code, D9-D0, ordered MSB-to-LSB in each case. Two don't-care bits, X1-X0, are loaded last. When the full 16-bit input word has been shifted in, $\overline{\text{CS/LD}}$ is pulled high, loading the DAC register with the word and causing the addressed DAC output(s) to update. The clock is disabled internally when $\overline{\text{CS/LD}}$ is high. Note: SCK must be low before $\overline{\text{CS/LD}}$ is pulled low.

The buffered serial output of the shift register is available on the D_{OUT} pin, which swings from GND to V_{CC} . Data appears on D_{OUT} 16 positive SCK edges after being applied to D_{IN} .

Multiple LTC1664's can be controlled from a single 3-wire serial port (i.e., SCK, D_{IN} and $\overline{\text{CS/LD}}$) by using the included daisychain facility. A series of m chips is configured by connecting each D_{OUT} (except the last) to D_{IN} of the next chip, forming a single $16m$ -bit shift register. The SCK and $\overline{\text{CS/LD}}$ signals are common to all chips in the chain. In use, $\overline{\text{CS/LD}}$ is held low while m 16-bit words are clocked to D_{IN} of the first chip; $\overline{\text{CS/LD}}$ is then pulled high, updating all of them simultaneously.

Sleep Mode

DAC address 1110_b is reserved for the special sleep instruction (see Table 2). In this mode, the digital interface stays active while the analog circuits are disabled; static power consumption is thus virtually eliminated. The reference input and analog outputs are set in a high impedance state and all DAC settings are retained in memory so that when sleep mode is exited, the outputs of DACs not updated by the Wake command are restored to their last active state.

Sleep mode is initiated by performing a load sequence to address 1110_b (the DAC input word D9-D0 is ignored). Once in sleep mode, a load sequence to any other address (including "No Change" address 0000_b) causes the LTC1664 to Wake. It is possible to keep one or more chips of a daisy chain in continuous sleep mode by giving the sleep instruction to these chips each time the active chips in the chain are updated.

Voltage Outputs

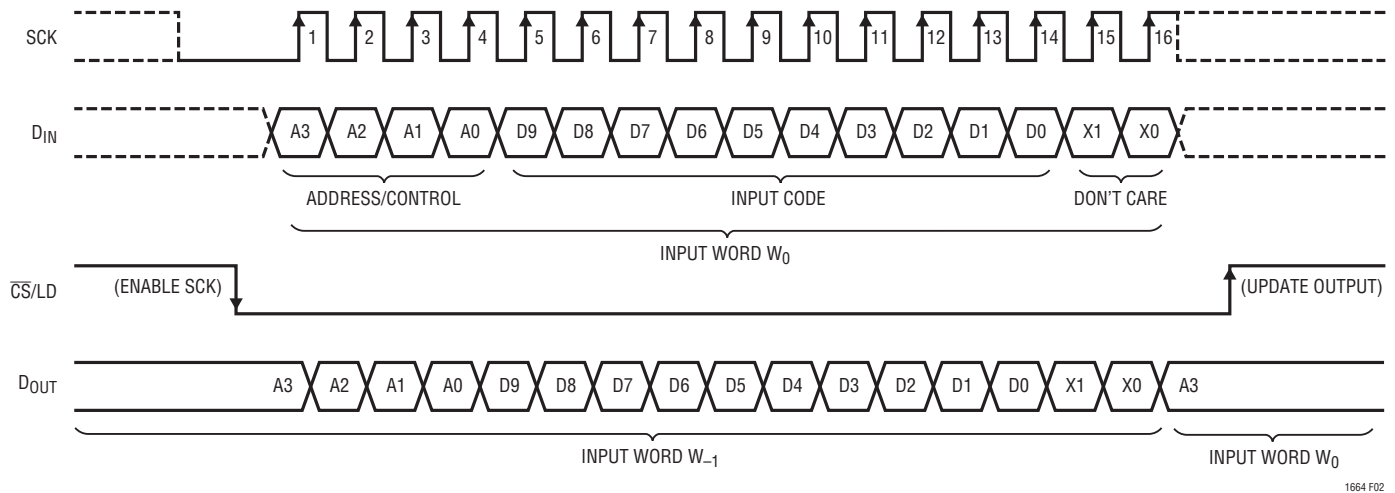
Each of the four rail-to-rail output amplifiers contained in the LTC1664 can source or sink up to 5mA. The outputs swing to within a few millivolts of either supply rail when unloaded and have an equivalent output resistance of 85Ω when driving a load to the rails. The output amplifiers are stable driving capacitive loads of up to 1000pF.

A small resistor placed in series with the output can be used to achieve stability for any load capacitance. A $1\mu\text{F}$

Table 1. LTC1664 Input Word

A3	A2	A1	A0	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	X1	X0
ADDRESS/CONTROL				INPUT CODE										DON'T CARE	

OPERATION



1664 F02

Figure 2. LTC1664 Register Loading Sequence

Table 2. DAC Address/Control Functions

ADDRESS/CONTROL				DAC STATUS	SLEEP STATUS
A3	A2	A1	A0		
0	0	0	0	No Change	Wake
0	0	0	1	Load DAC A	Wake
0	0	1	0	Load DAC B	Wake
0	0	1	1	Load DAC C	Wake
0	1	0	0	Load DAC D	Wake
0	1	0	1	Reserved	
0	1	1	0	Reserved	
0	1	1	1	Reserved	
1	0	0	0	Reserved	
1	0	0	1	Reserved	
1	0	1	0	Reserved	
1	0	1	1	Reserved	
1	1	0	0	Reserved	
1	1	0	1	Reserved	
1	1	1	0	No Change	Sleep
1	1	1	1	Load ALL DACs with Same 10-Bit Code	Wake

OPERATION

load can be successfully driven by inserting a 20Ω resistor; a $2.2\mu\text{F}$ load needs only a 10Ω resistor. In either case, larger values of resistance, capacitance or both may be safely substituted for the values given.

Rail-to-Rail Output Considerations

In any rail-to-rail voltage output DAC, the output is limited to voltages within the supply range.

If the DAC offset is negative, the output for the lowest codes limits at 0V as shown in Figure 3b.

Similarly, limiting can occur near full-scale when the REF pin is tied to V_{CC} . If $V_{REF} = V_{CC}$ and the DAC full-scale error (FSE) is positive, the output for the highest codes limits at V_{CC} as shown in Figure 3c. No full-scale limiting can occur if V_{REF} is less than $V_{CC} - \text{FSE}$.

Offset and linearity are defined and tested over the region of the DAC transfer function where no output limiting can occur.

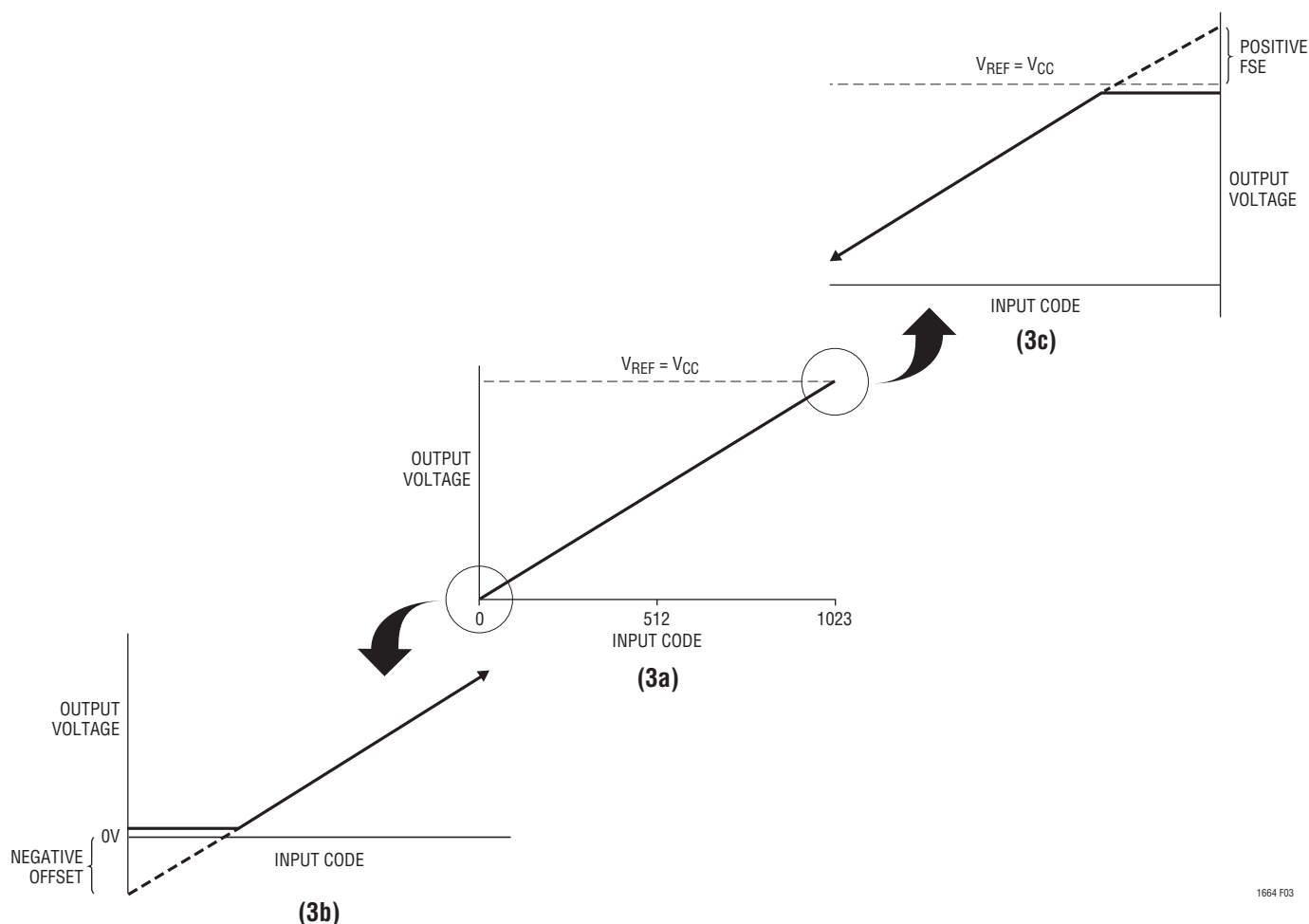


Figure 3. Effects of Rail-to-Rail Operation On a DAC Transfer Curve. (a) Overall Transfer Function (b) Effect of Negative Offset for Codes Near Zero-Scale (c) Effect of Positive Full-Scale Error for Input Codes Near Full-Scale When $V_{REF} = V_{CC}$

1664 F03

The schematic diagram illustrates the LTC1664 evaluation board. The central component is the LTC1664 chip, which contains four DACs (A, B, C, D) and a 3-wire serial interface. The chip is powered by a 3.3V source. The input and output buffers are implemented using LT1490 op-amps. The chip has four DACs (A, B, C, D) and a 3-wire serial interface (CS/LD, SCK, DOUT). The chip is connected to various components, including resistors (R1, R2), capacitors (0.1µF), and a 3.3V source. The chip has four DACs (A, B, C, D) and a 3-wire serial interface (CS/LD, SCK, DOUT). The chip is connected to various components, including resistors (R1, R2), capacitors (0.1µF), and a 3.3V source.

$$V_{OUT1} = V_{REF} \left(\frac{CODE\ A}{1024} + \frac{R1\ CODE\ B}{R2\ 1024} \right)$$

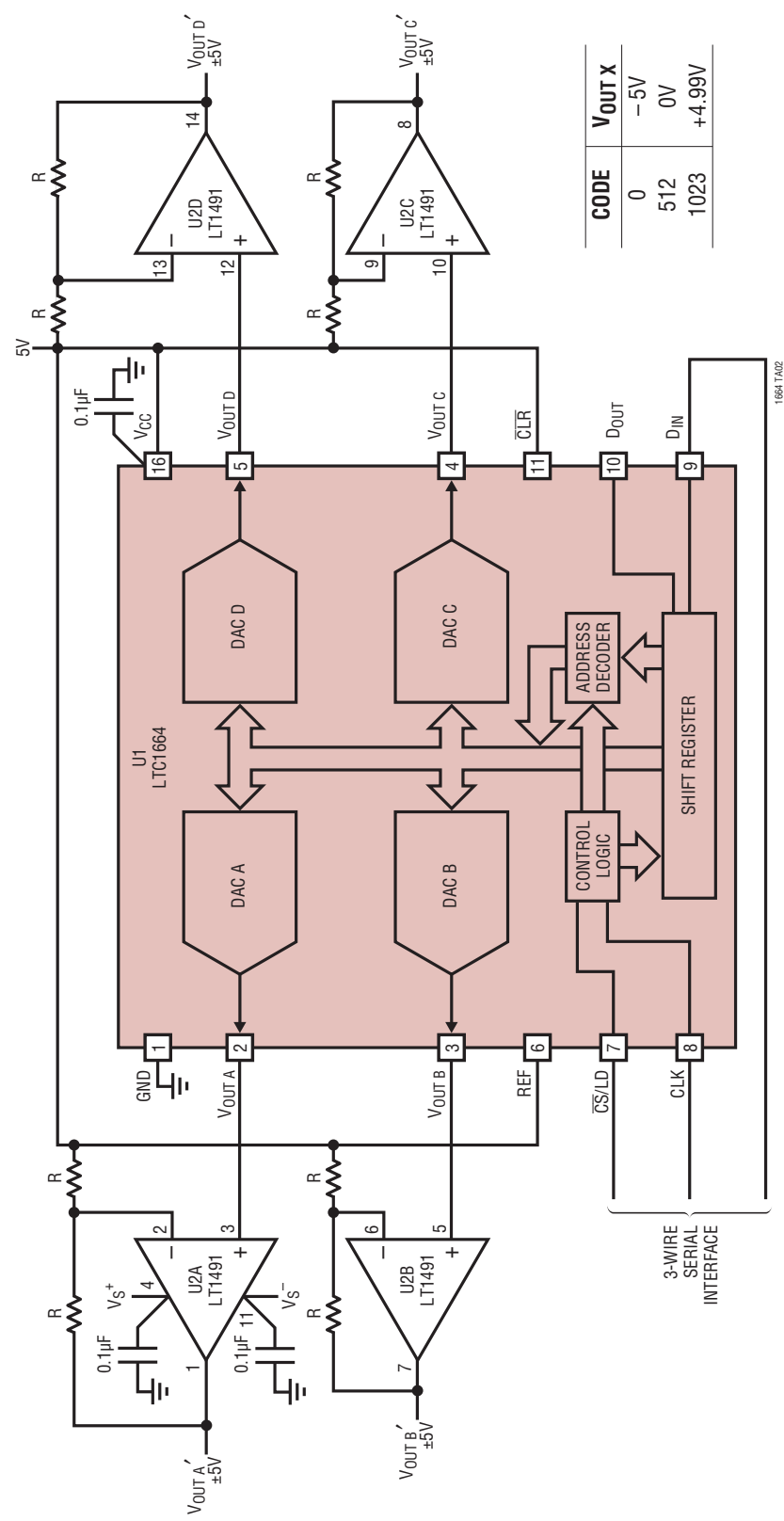
$$= 2.5V \left(\frac{\text{CODE A}}{1024} + \frac{1}{100} \frac{\text{CODE B}}{1024} \right)$$

$$V_{OUT2} = V_{REF} \left(\frac{CODE}{1024} + \frac{R1}{R2} \frac{CODE}{1024} \right)$$

$$= 2.5V \left(\frac{\text{CODED}}{1024} + \frac{1}{100} \frac{\text{CODEC}}{1024} \right)$$

TYPICAL APPLICATIONS

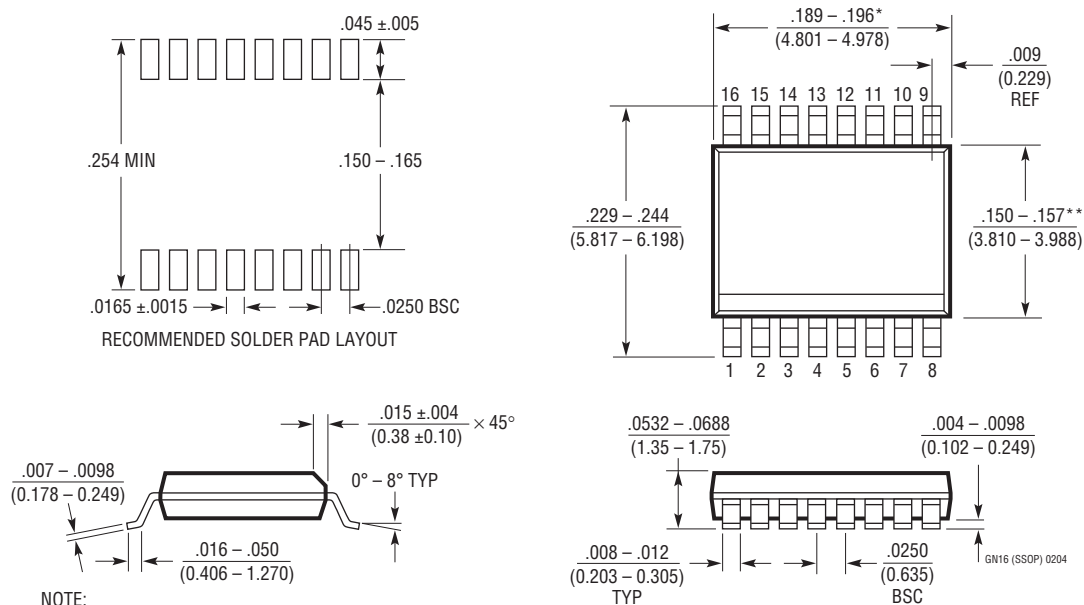
A 4-Channel Bipolar Output Voltage Circuit Configuration



PACKAGE DESCRIPTION

Please refer to <http://www.linear.com/designtools/packaging/> for the most recent package drawings.

GN Package 16-Lead Plastic SSOP (Narrow 0.150) (LTC DWG # 05-08-1641)



NOTE:

1. CONTROLLING DIMENSION: INCHES
2. DIMENSIONS ARE IN $\frac{\text{INCHES}}{\text{MILLIMETERS}}$
3. DRAWING NOT TO SCALE

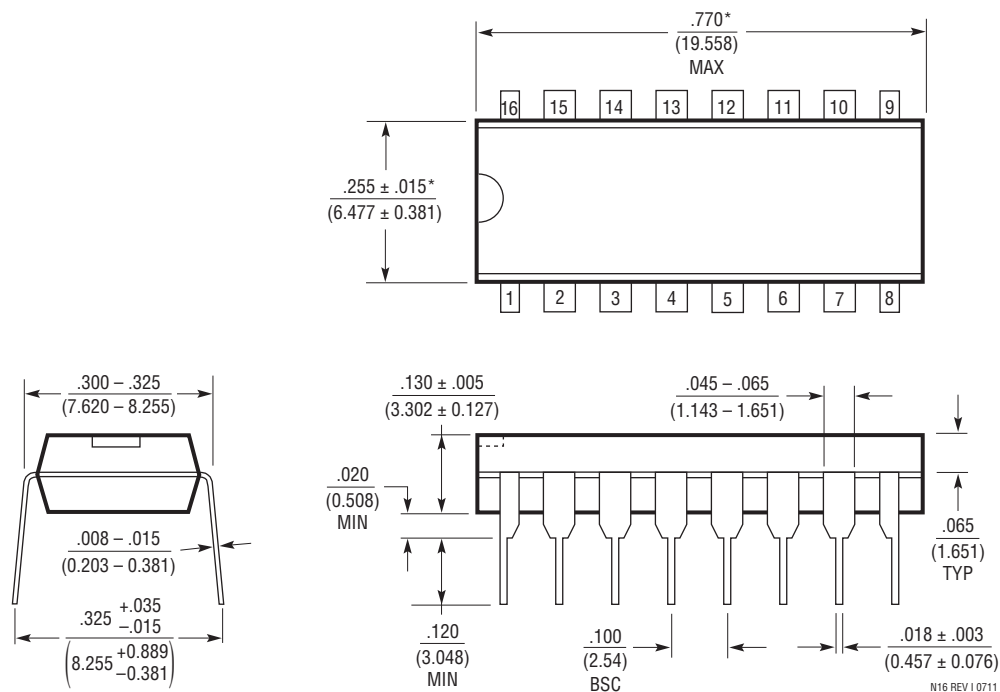
*DIMENSION DOES NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.006" (0.152mm) PER SIDE

**DIMENSION DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010" (0.254mm) PER SIDE

PACKAGE DESCRIPTION

Please refer to <http://www.linear.com/designtools/packaging/> for the most recent package drawings.

N Package 16-Lead PDIP (Narrow 0.300) (LTC DWG # 05-08-1510)



NOTE:
1. DIMENSIONS ARE $\frac{\text{INCHES}}{\text{MILLIMETERS}}$

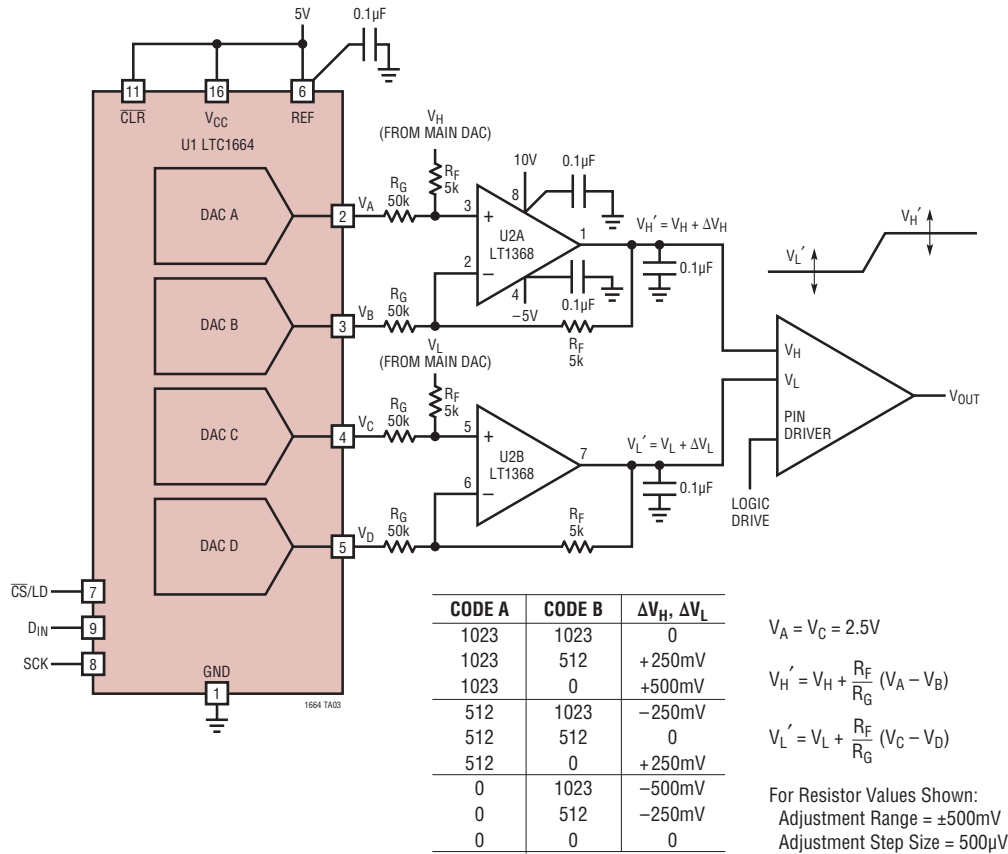
*THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 INCH (0.254mm)

REVISION HISTORY

REV	DATE	DESCRIPTION	PAGE NUMBER
A	01/12	Removed Typical values in the Timing Characteristics section. Corrected Related Parts listing for LTC1659.	4 16

TYPICAL APPLICATION

An 11-Bit Pin Driver V_H and V_L Adjustment Circuit for ATE Applications



RELATED PARTS

PART NUMBER	DESCRIPTION	COMMENTS
LTC1665/LTC1660	Octal 8-/10-Bit V_{OUT} DAC in 16-Pin Narrow SSOP	$V_{CC} = 2.7V$ to $5.5V$, $60\mu A$ per DAC, Rail-to-Rail Output
LTC1661	Dual 10-Bit V_{OUT} DAC in 8-Pin MSOP Package	$V_{CC} = 2.7V$ to $5.5V$, $60\mu A$ per DAC, Rail-to-Rail Output
LTC1662	Ultra Low Power Dual 10-Bit V_{OUT} DAC in 8-Pin MSOP Package	$V_{CC} = 2.7V$ to $5.5V$, $1.5\mu A$ per DAC, Rail-to-Rail Output
LTC1663	Single 10-Bit V_{OUT} DAC with 2-Wire Interface in SOT-23 Package	$V_{CC} = 2.7V$ to $5.5V$, Internal Reference, $60\mu A$
LTC1446/LTC1446L	Dual 12-Bit V_{OUT} DACs in SO-8 Package with Internal Reference	LTC1446: $V_{CC} = 4.5V$ to $5.5V$, $V_{OUT} = 0V$ to $4.095V$ LTC1446L: $V_{CC} = 2.7V$ to $5.5V$, $V_{OUT} = 0V$ to $2.5V$
LTC1448	Dual 12-Bit V_{OUT} DAC in SO-8 Package	$V_{CC} = 2.7V$ to $5.5V$, External Reference Can Be Tied to V_{CC}
LTC1454/LTC1454L	Dual 12-Bit V_{OUT} DACs in SO-16 Package with Added Functionality	LTC1454: $V_{CC} = 4.5V$ to $5.5V$, $V_{OUT} = 0V$ to $4.095V$ LTC1454L: $V_{CC} = 2.7V$ to $5.5V$, $V_{OUT} = 0V$ to $2.5V$
LTC1458/LTC1458L	Quad 12-Bit Rail-to-Rail Output DACs with Added Functionality	LTC1458: $V_{CC} = 4.5V$ to $5.5V$, $V_{OUT} = 0V$ to $4.095V$ LTC1458L: $V_{CC} = 2.7V$ to $5.5V$, $V_{OUT} = 0V$ to $2.5V$
LT1460	Micropower Precision Series Reference, 2.5V, 5V, 10V Versions	0.075% Max, 10ppm/°C Max, Only $130\mu A$ Supply Current
LTC1590	Dual 12-Bit I_{OUT} DAC in SO-16 Package	$V_{CC} = 4.5V$ to $5.5V$, 4-Quadrant Multiplication
LTC1654	Dual 14-Bit DAC in SO-8 Footprint	1LBS DNL, Selectable Speed/Power
LTC1659	Single Rail-to-Rail 12-Bit V_{OUT} DAC in 8-Lead MSOP Package	$V_{CC} = 2.7V$ to $5.5V$, Low Power Multiplying V_{OUT} DAC. Output Swings from GND to REF. REF Input Can Be Tied to V_{CC}

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